Taiwan Semiconductor

1A, 200V-1000V High Efficient Surface Mount Rectifier

FEATURES

- Glass passivated chip junction
- · Low power loss, high efficiency
- Fast switching for high efficiency
- Low profile package
- RoHS Compliant
- Halogen-free according to IEC 61249-2-21

APPLICATIONS

- DC to DC converter
- Switching mode converters and inverters
- Freewheeling application

MECHANICAL DATA

- Case: SOD-128
- Molding compound meets UL 94V-0 flammability rating
- Moisture sensitivity level: level 1, per J-STD-020
- Terminal: Matte tin plated leads, solderable per J-STD-002
- Meet JESD 201 class 2 whisker test
- Polarity: Indicated by cathode band
- Weight: 0.028g (approximately)

KEY PARAMETERS				
PARAMETER	VALUE	UNIT		
I _F	1	Α		
V_{RRM}	200 - 1000	V		
I _{FSM}	35	Α		
T _{J MAX}	150	°C		
Package	SOD-128			
Configuration	Single die			





SOD-128



PARAMETER		SYMBOL	HS1DFS	HS1GFS	HS1JFS	HS1KFS	HS1MFS	UNIT
Marking code on the device			HS1DFS	HS1GFS	HS1JFS	HS1KFS	HS1MFS	
Repetitive peak rever	rse voltage	V_{RRM}	200	400	600	800	1000	V
Reverse voltage, total rms value		V _{R(RMS)}	140	280	420	560	700	V
Forward current		I _F	1					Α
Surge peak forward current, single half sine-wave superimposed on rated load $t = 8.3 \text{ms}$					35			А
		I _{FSM}			90			А
Junction temperature	;	TJ	-55 to +150			°C		
Storage temperature T _{STG}		-55 to +150				°C		



THERMAL PERFORMANCE				
PARAMETER	SYMBOL	TYP	UNIT	
Junction-to-lead thermal resistance	$R_{\Theta JL}$	29	°C/W	
Junction-to-ambient thermal resistance	$R_{\Theta JA}$	51	°C/W	
Junction-to-case thermal resistance	R _{eJC}	22	°C/W	

Thermal Performance Note: Units mounted on PCB (5mm x 5mm Cu pad test board)

PARAMETER		CONDITIONS	SYMBOL	TYP	MAX	UNIT
	HS1DFS	I _F = 0.5A, T _J = 25°C		0.80	-	V
		I _F = 1.0A, T _J = 25°C		0.85	1.00	V
		I _F = 0.5A, T _J = 125°C		0.65	-	V
		I _F = 1.0A, T _J = 125°C	1	0.71	0.80	V
		$I_F = 0.5A, T_J = 25^{\circ}C$		0.84	-	V
	HS1GFS	I _F = 1.0A, T _J = 25°C		0.91	1.30	V
	потого	I _F = 0.5A, T _J = 125°C		0.68	-	V
Forward voltage ⁽¹⁾		I _F = 1.0A, T _J = 125°C	V_{F}	0.76	0.86	V
roiward vollage		$I_F = 0.5A, T_J = 25^{\circ}C$	VF	0.92	-	V
	HS1JFS	$I_F = 1.0A, T_J = 25^{\circ}C$		1.02	1.70	V
		$I_F = 0.5A, T_J = 125$ °C		0.73	-	V
		I _F = 1.0A, T _J = 125°C		0.83	1.02	V
	HS1KFS HS1MFS	$I_F = 0.5A, T_J = 25^{\circ}C$		1.32	-	V
		$I_F = 1.0A, T_J = 25^{\circ}C$		1.49	1.70	V
		$I_F = 0.5A, T_J = 125$ °C		0.98	-	V
		$I_F = 1.0A, T_J = 125$ °C		1.16	1.39	V
Reverse current @ rated V _R ⁽²⁾		T _J = 25°C	· I _R	-	1	μA
ineverse current & rated v _R		T _J = 125°C	'R	-	35	μΑ
Reverse recovery time	HS1DFS HS1GFS	I _F = 0.5A, I _R = 1.0A,		-	50	ns
	HS1JFS HS1KFS HS1MFS	$I_{rr} = 0.25A$	t _{rr}	-	75	ns
Junction capacitance	HS1DFS			20	-	pF
	HS1GFS			17	-	pF
	HS1JFS	$1MHz$, $V_R = 4.0V$	C _J	13	-	pF
	HS1KFS HS1MFS			8	-	pF

Notes:

- 1. Pulse test with PW = 0.3ms
- 2. Pulse test with PW = 30ms



ORDERING INFORMATION			
ORDERING CODE ⁽¹⁾	PACKAGE	PACKING	
HS1xFS	SOD-128	14,000 / Tape & Reel	

Notes:

1. "x" defines voltage from 200V(HS1DFS) to 1000V(HS1MFS)



CHARACTERISTICS CURVES

 $(T_A = 25^{\circ}C \text{ unless otherwise noted})$

Fig.1 Forward Current Derating Curve

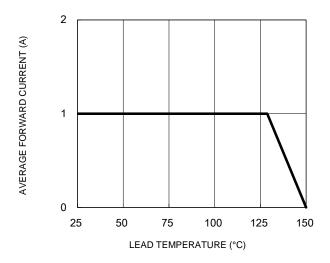


Fig.3 Typical Reverse Characteristics

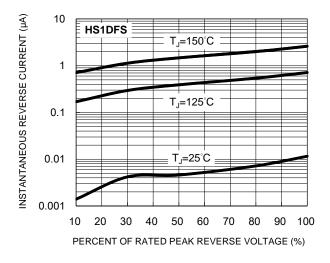


Fig.5 Typical Reverse Characteristics

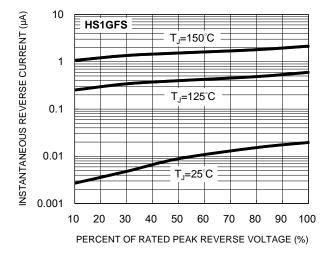


Fig.2 Typical Junction Capacitance

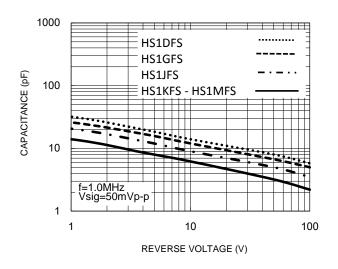


Fig.4 Typical Forward Characteristics

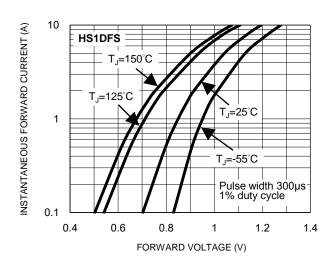
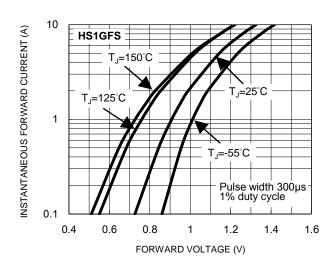


Fig.6 Typical Forward Characteristics





CHARACTERISTICS CURVES

 $(T_A = 25^{\circ}C \text{ unless otherwise noted})$

Fig.7 Typical Reverse Characteristics

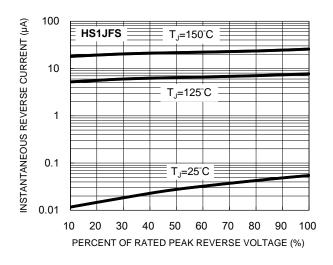


Fig.9 Typical Reverse Characteristics

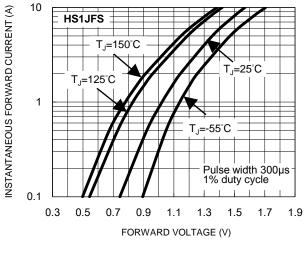
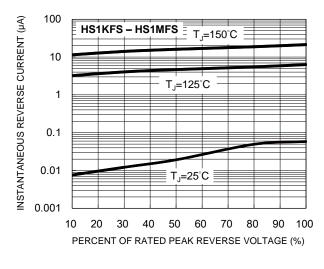


Fig.8 Typical Forward Characteristics

Fig.10 Typical Forward Characteristics



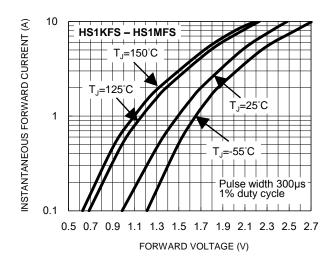
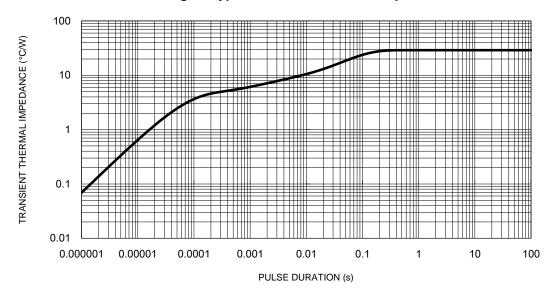


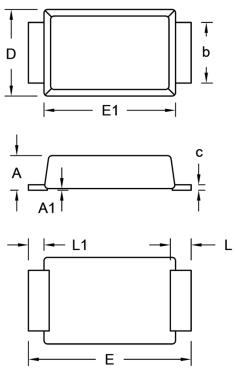
Fig.11 Typical Transient Thermal Impedance





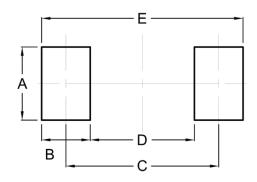
PACKAGE OUTLINE DIMENSIONS

SOD-128



DIM.	Unit	Unit (mm)		(inch)
DIIVI.	Min.	Max.	Min.	Max.
Α	0.90	1.10	0.035	0.043
A1	0.00	0.10	0.000	0.004
b	1.60	1.90	0.063	0.075
С	0.10	0.22	0.004	0.009
D	2.30	2.70	0.091	0.106
E	4.40	5.00	0.173	0.197
E1	3.60	4.00	0.142	0.157
L	0.40	0.80	0.016	0.031
L1	0.30	0.60	0.012	0.024

SUGGESTED PAD LAYOUT



Symbol	Unit (mm)	Unit (inch)
Α	2.10	0.083
В	1.40	0.055
С	4.40	0.173
D	3.00	0.118
E	5.80	0.228

MARKING DIAGRAM



P/N = Marking Code YW = Date Code = Factory Code



Taiwan Semiconductor

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